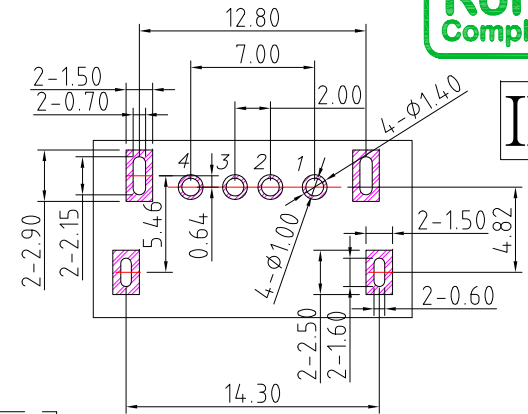




SUA-WP110H53-x-S165

Insulation Housin Color :

| |
|-----------|
| Black: B |
| White : W |



IPX8

PCB LAYOUT

PIN ASSIGNMENT

| PIN NO. | 1 | 2 | 3 | 4 |
|-------------|------|----|----|-----|
| SINGAL NAME | VBUS | D- | D+ | GND |

SPECIFICATIONS

Electrical:

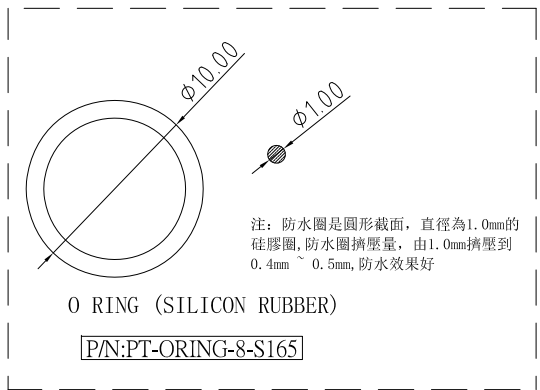
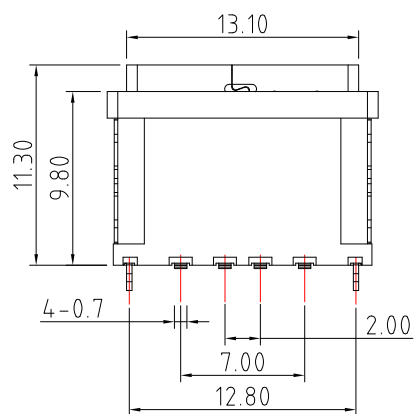
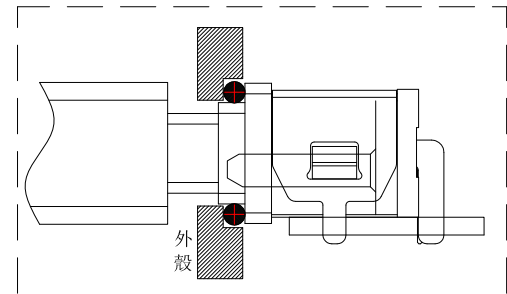
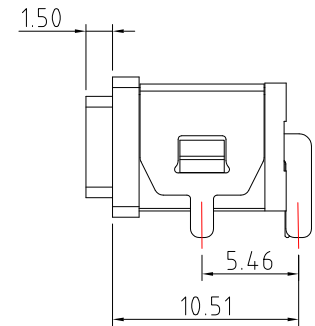
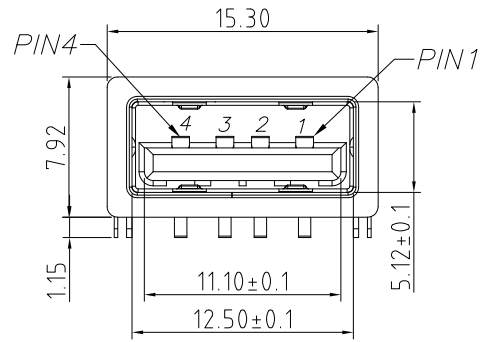
- 1.Rating: 3.0A
- 1.Contact Resistance: 40 mΩ Max
- 2.Insulation Resistance: 100 MΩ Min
- 3.Dielectric Withstanding Voltage: 100V AC

Material:

- 1.Insulation Housing: PA10T
- 2.Contact: Brass
- 3.Shell: SUS

Finish:

- 1.Contact: Plated Gold in Mating Area ;
Gold Plated on Solder Balls
Nickel under plated overall



CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

| | | | | |
|-------------------------------------|--------------------|--------------|-------|----|
| TOLERANCE UNLESS OTHERWISE STATED : | Up to 5 ±0.2 | 3RD. ANGEL'S | UNITS | MM |
| | Above 5 ~ 30 ±0.3 | | | |
| | Above 30 ~ 50 ±0.4 | | | |
| | Above 50 ±0.5 | | | |
| | Angle ±0.3° | | | |

| | | | | |
|--------------|----------|-----------|----------|--------------------------|
| DRAWN BY: | DATE | MAT'L | TITLE | CONNECTOR |
| Jack Lu | 07/31/20 | | | |
| CHECKED BY: | DATE | FINISH | MODLE | USB 2.0 AF RA WATERPROOF |
| Jacky Chen | 07/31/20 | | | |
| APPROVED BY: | DATE | SCALE | DWG NO. | SUA-WP110H53-x-S165 |
| Tony Kao | 07/31/20 | 1 : 1 | PART NO. | SUA-WP110H53-x-S165 |
| | | SHEET NO. | 1 of 1 | |

| | | | |
|----------|----------------|-------|--------|
| ITEM NO. | DESCRIPTION | DRAWN | DATE |
| 1 | 新增PCB LAYOUT尺寸 | Jack | 073120 |